Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.063”**

**.069”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: B = .009 X .050 E = .009 X .042”**

**Backside Potential: collector**

**Mask Ref: 269**

**APPROVED BY: DK DIE SIZE .063” X .069” DATE: 3/31/17**

**MFG: SOLITRON THICKNESS .010” P/N: 2N5001**

**DG 10.1.2**

#### Rev B, 7/1